ABSTRACT

Mechanical method permitting a change in position of at least one semiconductor wafer (2) provided with at least one positioning mark (3) and placed in a support intended to house a plurality of semiconductor wafers, comprising the following steps:

- penetrating the support by means of a gripping arm (1) with a first displacement of the arm in a first spatial direction (Y),
- gripping the semiconductor wafer by its peripheral part (4) with a second displacement of the arm in a second spatial direction (Z),
- orientating the gripped wafer so as to place the positioning mark in a defined position.

Device permitting a change in position of a semiconductor wafer (2) provided with a positioning mark (3) and placed in a support intended to house a plurality of semiconductor wafers, the device comprising an arm for gripping the wafer and means for displacing the arm, the latter comprising:

- means for gripping the semiconductor wafer by the peripheral part,
- means for orientating the wafer, which means co-operate with the gripping means in order to place the positioning mark in a defined position,

the displacement means (120) of the gripping arm (1) comprising means for displacement in three spatial directions (X, Y, Z), the gripping means (5) and the orientation means (6) being disposed on a rigid structure (7), the gripping means being distributed over the perimeter of the peripheral part of the semiconductor wafer.

Fig. 2

This Sheet Has Been Replaced

